## **MULTI-ROW BOARD-TO-BOARD CONNECTOR**

Enhances design flexibility for **high-density** connections with our **automotive-compliant**, stackable connector designed with **snap-in biscuit design**, allowing for cost savings.



### HIGHLY CONFIGURABLE

Multiple connector units can be stacked together, with pin and board spacing options.



### PLUGGABLE AND RELIABLE

Very low levels of contact resistance ( $<1m\Omega$ ).



### **AUTOMOTIVE-COMPLIANT**

- Conforms to automotive performance requirements.
- Meet IEC60352-5 and IPC-9797 standards.

## INTERPLEX 0.4 MINIPLX™ WITH INDICOAT™ PLATING

- > Current rating: 3 Amps/pin
- > Option for IndiCoat™, Interplex's proprietary whisker mitigation plating technology

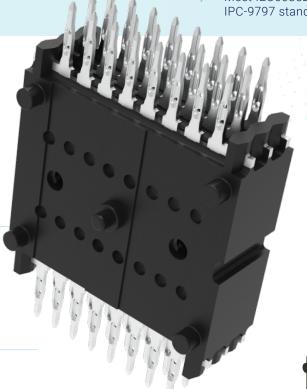
## 4 TO 30 CIRCUITS PER ROW; 1 TO 6 ROWS

> 1.8mm pin-to-pin spacing with 2mm row-to-row spacing

# 7MM TO 30MM BOARD TO BOARD SPACING

## HIGH PERFORMANCE MATERIAL

- > Relative humidity (RH): 80% to 100%, 8-hour cycling
- > Working temperature range: -40°C to +150°C
- **Mechanical shock:** 35g for 5 to 10ms across 10 axes
- Vibration: 8 hour per axisVoltage: 500V DC ±10%
- > Insulation resistance: ≥100 MΩ



Snap-in Biscuit Design:



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